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Reply under 37 CFR 1.116
Expedited Procedure
Technology Center 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Morrison, et al.

Serial No.: 10/034,827

Filed: 01/03/02

For: Chip-Scale Packages Stacked on Folded Interconnector for Vertical Assembly
on Substrates

Conf. No. 4496

Docket No.: TI-31373

Examiner: Mitchell, J. M.

Art Unit: 2827

Amendment under 37 CFR 1.116

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on

August 18, 2003.

Elizabeth Austin

Elizabeth Austin

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 06/16/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.